

COATING METHOD OF ELECTRIC OR ELECTRONIC PARTS

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Inventor: KOBER SUSANNE; WIPFELDER ERNST
Applicant: SIEMENS AG
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Abstract of JP5220767

PURPOSE: To coat a pressure-sensitive part securely without stress and maintain the fluctuations of part's parameters due to coating within the tolerance limit during and after thermal load by filling a filler into the mold which houses the part and by injecting a low-viscous reactive resin onto the filler at a low speed so as not to leave any cavity inside.

CONSTITUTION: The filler to be filled into the mold is required to have fluidity and to be fine powder such as quartz powder, and desirable to have a lower thermal expansion coefficient than reactive resin and an average particle size of 10-20 μm . Moreover, the filler is desirable to become consolidated by vibration and the like of the mold before the injection of the reactive resin. As the reactive resin, epoxy resin/anhydride to which a plasticizer is added is desirable. For example, a surface packaging inductor 1 is equipped with coils 3 having windings 4 around the central foot of a double E-type magnetic core 2 made of ferrite, and the magnetic core 2 is housed in a plastic container 5. In this case, the injection-type resin is cast by this method into the spaces 6 and 7 between the magnetic core 2 and the windings 4 and between the magnetic core 2 and the container 5, respectively.

